

WHAT IS CLAIMED IS:

1. A circuit board comprising:

a terminal portion connected with an external terminal formed in an external circuit, said terminal portion provided

5 with a nickel plating layer and a soldering bump;

wherein a thickness of said nickel plating layer is within a range of 1.0 to 4.0 μm .

2. A circuit board according to Claim 1, wherein said soldering bump contains tin and at least one of silver and copper.

3. A circuit board according to Claim 1, wherein said soldering bump contains tin, silver and copper.

15

4. A circuit board according to Claim 1, wherein said circuit board is a circuit-provided suspension substrate.

5. A connection structure for connecting a terminal portion of a circuit board with an external terminal formed in an external circuit, wherein said terminal portion is provided with a nickel plating layer and a soldering bump provided on said terminal portion and a thickness of said nickel plating layer is within a range of 1.0 to 4.0 μm .

20